

T496X226M035ATE300

General Information

Series Dielectric

Style

Description

Features

T496, Tantalum, MnO2 Tantalum, Fused, 22 uF, 20%, 35 VDC, SMD, MnO2, Molded, Fused, N/A, 300 mOhms, 7343, 4.3 mm, 1.3 mm

T496

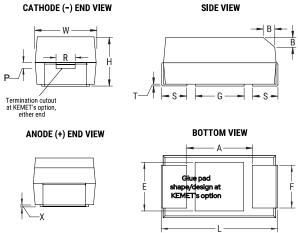
MnO2 Tantalum

SMD, MnO2, Molded, Fused

SMD Chip

Integral Fuse





ANODE (+) END VIEW	BOTTOM VIEW	RoHS	Yes
		Termination	Tin
	Glue pad shape/design at KEMET's option	AEC-Q200	No
		Typical Component Weight	652.04 mg
		Shelf Life	156 Weeks
	L	MSL	1
Click here for	the 3D model.		
Dimensions		Specifications	
L	7.3mm +/-0.3mm	Capacitance	22 uF
W	4mm +/-0.3mm	Tolerance	20%
Н	4mm +/-0.3mm	Voltage DC	35 VDC (85C), 23.45 VDC
Т	0.13mm REF		(125C)
S	1.3mm +/-0.3mm	Temperature Range	-55/+125°C

L	7.3mm +/-0.3mm
W	4mm +/-0.3mm
Н	4mm +/-0.3mm
Т	0.13mm REF
S	1.3mm +/-0.3mm
F	2.4mm +/-0.1mm
Α	3.8mm MIN
В	0.5mm +/-0.15mm
E	3.5mm REF
G	3.5mm REF
Р	1.7mm REF
R	1mm REF
X	0.1mm +/-0.1mm REF

Packaging Specifications	
Packaging	T&R, 178mm
Packaging Quantity	500

Specifications	
Capacitance	22 uF
Tolerance	20%
Voltage DC	35 VDC (85C), 23.45 VDC (125C)
Temperature Range	-55/+125°C
Rated Temperature	85°C
Dissipation Factor	6% 120Hz 25C
Failure Rate	N/A
ESR	300 mOhms (100kHz 25C)
Ripple Current	742 mA (rms, 100kHz 25C), 667.8 mA (rms, 85C), 296.8 mA (rms, 125C)
Leakage Current	7.7 uA (5min 25°C)

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

Generated 05/04/2025 © 2006 - 2025 YAGEO

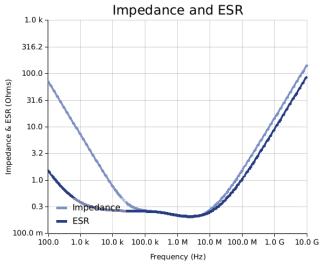


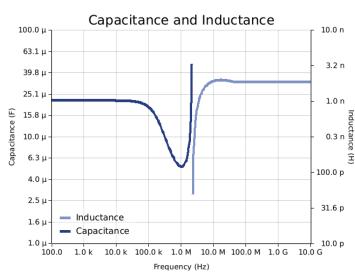


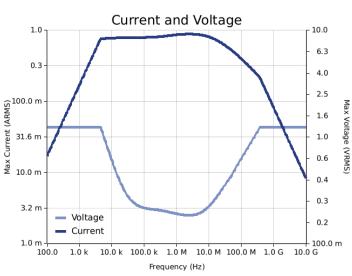
T496, Tantalum, MnO2 Tantalum, Fused, 22 uF, 20%, 35 VDC, SMD, MnO2, Molded, Fused, N/A, 300 mOhms, 7343, 4.3 mm, 1.3 mm

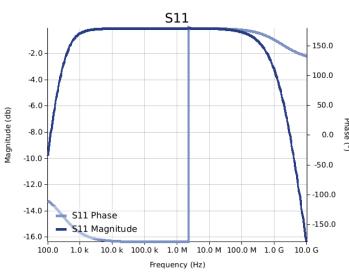
Simulations

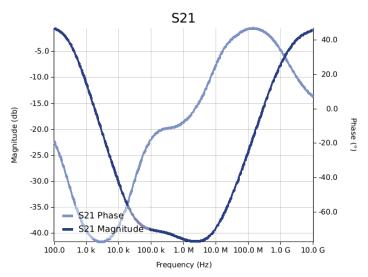
For the complete simulation environment please visit K-SIM.











Generated 05/04/2025 © 2006 - 2025 YAGEO



T496X226M035ATE300

T496, Tantalum, MnO2 Tantalum, Fused, 22 uF, 20%, 35 VDC, SMD, MnO2, Molded, Fused, N/A, 300 mOhms, 7343, 4.3 mm, 1.3 mm

These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.

- The ESR used for ripple Ripple Currenty votage vs. rrequency plots is unleast at an interact temperature.
 The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
 The effects shown herein are based on measured data from a multiple part sample of the parts in question.
 Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.
 The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages
- generated at any other harmonics.

 Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

All Information given herein is believed to be accurate and reliable, but is presented without guarantee, warranty, or responsibility of any kind, expressed or implied. Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute – and we specifically disclaim – any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

If you have any questions please contact K-SIM.

Generated 05/04/2025 © 2006 - 2025 YAGEO